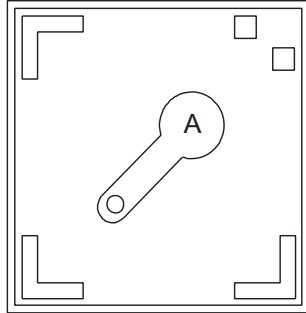


CPD65-BAV45

Low Leakage Diode Die

50mA, 35 Volt

The CPD65-BAV45 is a silicon 50mA, 35 Volt diode ideal for low leakage applications.



MECHANICAL SPECIFICATIONS:

Die Size	11.8 x 11.8 MILS
Die Thickness	8.0 MILS
Anode Bonding Pad Size	2.35 MILS DIAMETER
Top Side Metalization	Al – 15,000Å
Back Side Metalization	Au – 18,000Å
Scribe Alley Width	2.5 MILS
Wafer Diameter	4 INCHES
Gross Die Per Wafer	75,000

MAXIMUM RATINGS: (T_A=25°C)

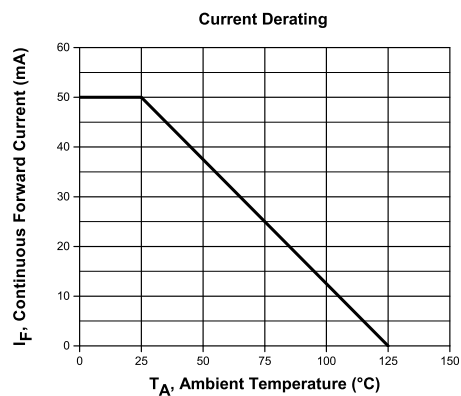
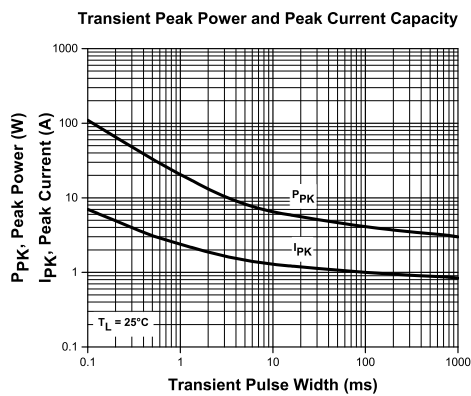
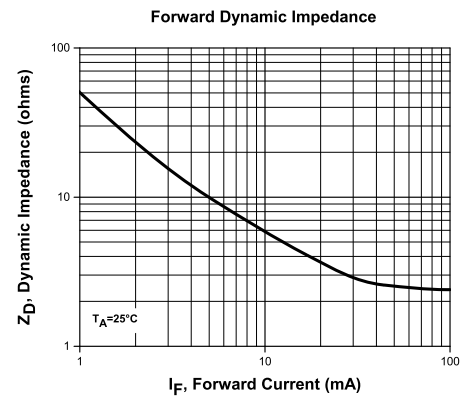
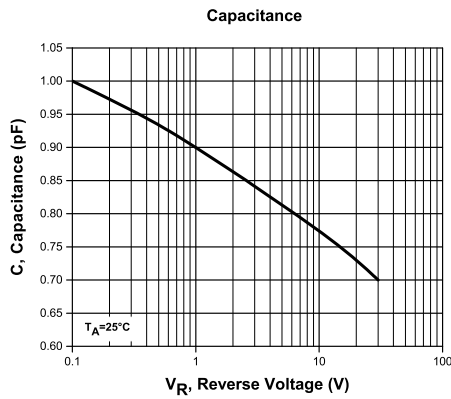
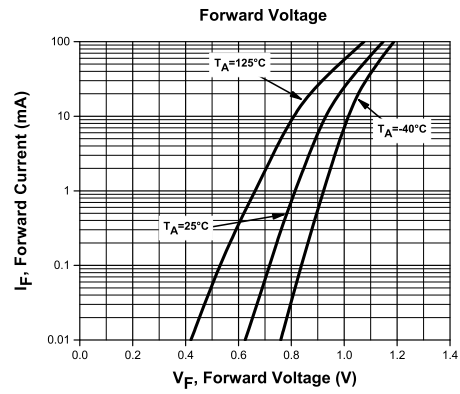
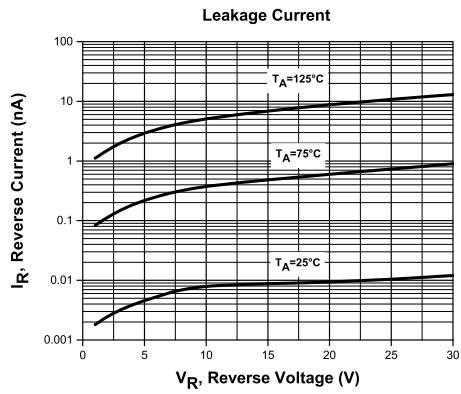
	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	35	V
Continuous Reverse Voltage	V _R	20	V
Continuous Forward Current	I _F	50	mA
Peak Repetitive Forward Current	I _{FRM}	100	mA
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +125	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

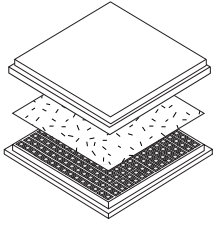
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _R	V _R =5.0V		5.0	pA
I _R	V _R =20V		10	pA
V _F	I _F =10mA		1.0	V
C _J	V _R =0, f=1.0MHz		1.3	pF
t _{rr}	I _F =I _R =10mA, I _{rr} =1.0mA, R _L =100Ω		600	ns

CPD65-BAV45

Typical Electrical Characteristics



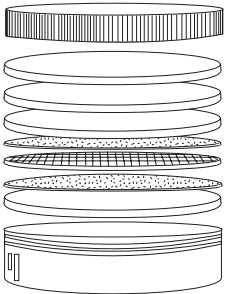
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

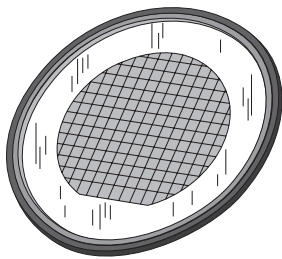
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

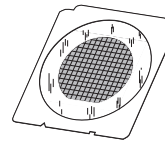
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

R2 (3-April 2017)

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Central's operations team provides the highest level of support to insure product is delivered on-time.

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- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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